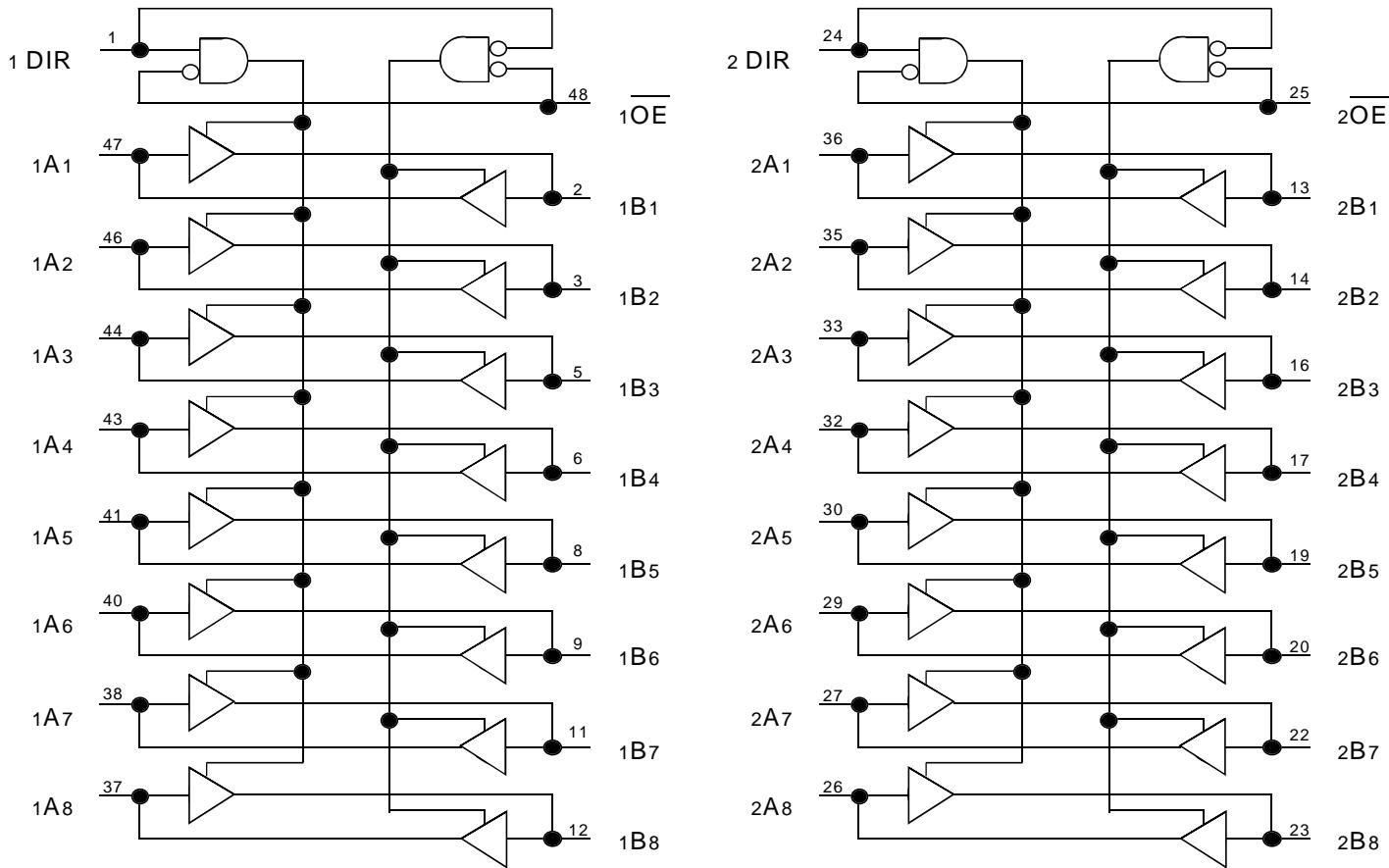


FEATURES:

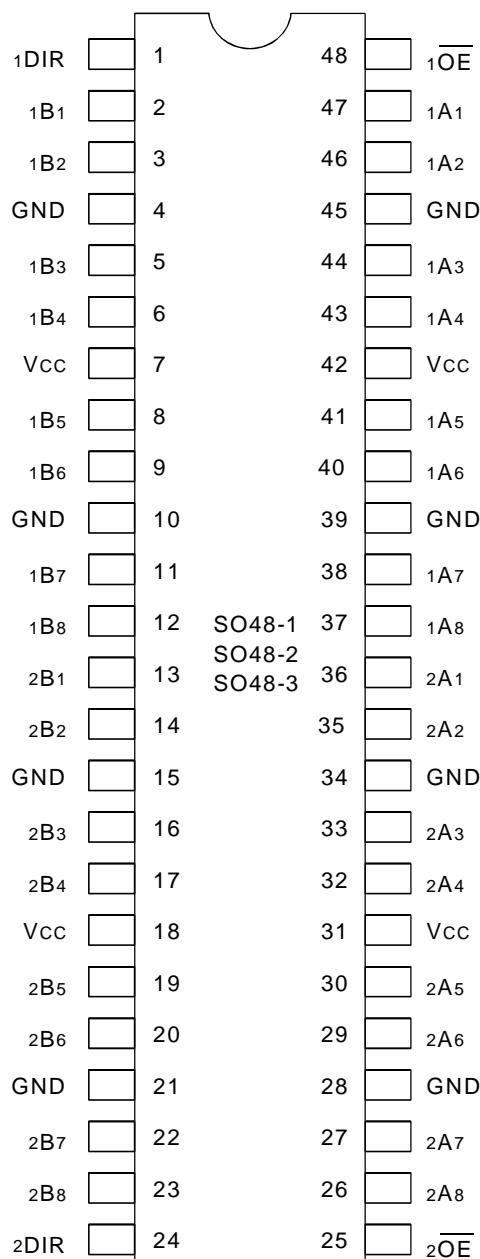
- 0.5 MICRON CMOS Technology
- Typical $t_{sk(o)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015;
> 200V using machine model ($C = 200\text{pF}$, $R = 0$)
- $V_{cc} = 3.3V \pm 0.3V$, Normal Range or $V_{cc} = 2.7V$ to 3.6V, Extended Range
- CMOS power levels ($0.4\mu\text{W}$ typ. static)
- Rail-to-Rail output swing for increased noise margin
- Low Ground Bounce (0.3V typ.)
- Inputs (except I/O) can be driven by 3.3V or 5V components
- Available in SSOP, TSSOP and TVSOP Packages

DESCRIPTION:

The FCT163245/A/C 16-bit transceivers are built using advanced dual metal CMOS technology. These high-speed, low-power transceivers are ideal for asynchronous communication between two buses (A and B). The Direction and Output Enable controls are designed to operate these devices as either two independent 8-bit transceivers or one 16-bit transceiver. The direction control pin (xDIR) controls the direction of data flow. The output enable pin ($x\bar{OE}$) overrides the direction control and disables both ports. All inputs are designed with hysteresis for improved noise margin.

FUNCTIONAL BLOCK DIAGRAM


PIN CONFIGURATION



SSOP/ TSSOP/ TVSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to +7	V
VTERM ⁽⁴⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-60 to +60	mA

3v16-link

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- Vcc terminals.
- Input terminals.
- Outputs and I/O terminals.

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	3.5	6	pF
COUT	Output Capacitance	VOUT = 0V	3.5	8	pF

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NOTE:

- This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
xOE	Output Enable Input (Active LOW)
xDIR	Direction Control Input
xAx	Side A Inputs or 3-State Outputs
xBx	Side B Inputs or 3-State Outputs

FUNCTION TABLE⁽¹⁾

Inputs		Outputs
xOE	xDIR	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	High Z State

NOTE:

- H = HIGH Voltage Level
- L = LOW Voltage Level
- X = Don't Care
- Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $V_{CC} = 2.7\text{V}$ to 3.6V

Symbol	Parameter	Test Conditions ⁽¹⁾			Min.	Typ. ⁽²⁾	Max.	Unit		
V_{IH}	Input HIGH Level (Input pins)	Guaranteed Logic HIGH Level	2	—	5.5	V	$V_{CC} + 0.5$			
	Input HIGH Level (I/O pins)									
V_{IL}	Input LOW Level (Input and I/O pins)	Guaranteed Logic LOW Level			−0.5	—	0.8	V		
I_{IH}	Input HIGH Current (Input pins)	$V_{CC} = \text{Max.}$	$V_I = 5.5\text{V}$	—	—	± 1	μA			
	Input HIGH Current (I/O pins)									
I_{IL}	Input LOW Current (Input pins)	$V_{CC} = \text{Max.}$	$V_I = \text{GND}$	—	—	± 1	μA			
	Input LOW Current (I/O pins)									
I_{OZH}	High Impedance Output Current (3-State Output pins)	$V_{CC} = \text{Max.}$	$V_O = V_{CC}$	—	—	± 1	μA			
I_{OZL}										
V_{IK}	Clamp Diode Voltage	$V_{CC} = \text{Min.}$, $I_{IN} = -18\text{mA}$			—	−0.7	−1.2	V		
I_{ODH}	Output HIGH Current	$V_{CC} = 3.3\text{V}$, $V_{IN} = V_{IH}$ or V_{IL} , $V_O = 1.5\text{V}$ ⁽³⁾								
I_{ODL}	Output LOW Current	$V_{CC} = 3.3\text{V}$, $V_{IN} = V_{IH}$ or V_{IL} , $V_O = 1.5\text{V}$ ⁽³⁾			50	90	200	mA		
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -0.1\text{mA}$ $I_{OH} = -3\text{mA}$	$V_{CC} - 0.2$	—	—	V			
		$V_{CC} = 3\text{V}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -8\text{mA}$	$2.4^{(5)}$	3	—				
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 0.1\text{mA}$ $I_{OL} = 16\text{mA}$	$V_{CC} - 0.2$	—	0.2	V			
		$V_{CC} = 3\text{V}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 24\text{mA}$	$2.4^{(5)}$	3	—				
I_{OS}	Short Circuit Current ⁽⁴⁾	$V_{CC} = \text{Max.}$, $V_O = \text{GND}$ ⁽³⁾			−60	−135	−240	mA		
V_H	Input Hysteresis	—								
I_{CCL} I_{CCH} I_{CCZ}	Quiescent Power Supply Current	$V_{CC} = \text{Max.}$ $V_{IN} = \text{GND}$ or V_{CC}			—	0.1	10	μA		

3v16-link

NOTES:

- For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at $V_{CC} = 3.3\text{V}$, $+25^\circ\text{C}$ ambient.
- Not more than one output should be tested at one time. Duration of the test should not exceed one second.
- This parameter is guaranteed but not tested.
- $V_{OH} = V_{CC} - 0.6\text{V}$ at rated current.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	V _{CC} = Max.	V _{IN} = V _{CC} – 0.6V ⁽³⁾	—	2	30	µA
I _{CCD}	Dynamic Power Supply Current ⁽⁴⁾	V _{CC} = Max. Outputs Open $x\bar{OE} = xDIR = GND$ One Input Toggling 50% Duty Cycle	V _{IN} = V _{CC} V _{IN} = GND	—	50	75	µA/ MHz
I _C	Total Power Supply Current ⁽⁶⁾	V _{CC} = Max. Outputs Open $f_i = 10MHz$	V _{IN} = V _{CC} V _{IN} = GND	—	0.5	0.8	mA
		50% Duty Cycle $x\bar{OE} = xDIR = GND$ One Bit Toggling	V _{IN} = V _{CC} – 0.6V V _{IN} = GND	—	0.5	0.8	
		V _{CC} = Max. Outputs Open $f_i = 2.5MHz$	V _{IN} = V _{CC} V _{IN} = GND	—	2	3 ⁽⁵⁾	
		50% Duty Cycle $x\bar{OE} = xDIR = GND$ Sixteen Bits Toggling	V _{IN} = V _{CC} – 0.6V V _{IN} = GND	—	2	3.3 ⁽⁵⁾	

NOTES:

1. For conditions shown as max. or min., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at V_{CC} = 3.3V, +25°C ambient.

3. Per TTL driven input; all other inputs at V_{CC} or GND.

4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.

5. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

6. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$

$$I_C = I_{CC} + \Delta I_{CC} D_{HNT} + I_{CCD} (f_{CP} N_{CP}/2 + f_i N_i)$$

I_{CC} = Quiescent Current (I_{CCL}, I_{CH} and I_{CCZ})

ΔI_{CC} = Power Supply Current for a TTL High Input

D_H = Duty Cycle for TTL Inputs High

N_T = Number of TTL Inputs at D_H

I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)

N_{CP} = Number of Clock Inputs at f_{CP}

f_i = Input Frequency

N_i = Number of Inputs at f_i

SWITCHING CHARACTERISTICS OVER OPERATING RANGE (4)

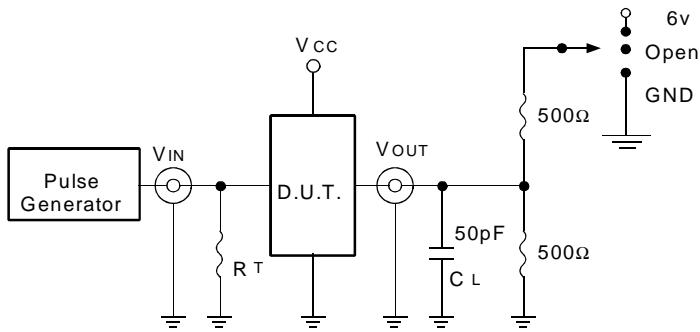
Symbol	Parameter	Condition ⁽¹⁾	FCT163245		FCT163245A		FCT163245C		Unit
			Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	
tPLH	Propagation Delay A to B, B to A	CL = 50pF RL = 500Ω	1.5	7	1.5	4.6	1.5	4.1	ns
tpZH	Output Enable Time xOE to A or B		1.5	9.5	1.5	6.2	1.5	5.8	ns
tPHZ	Output Disable Time xOE to A or B		1.5	7.5	1.5	5	1.5	4.8	ns
tpZH	Output Enable Time xDIR to A or B ⁽⁵⁾		1.5	9.5	1.5	6.2	1.5	5.8	ns
tPHZ	Output Disable Time xDIR to A or B ⁽⁵⁾		1.5	7.5	1.5	5	1.5	4.8	ns
tsk(o)	Output Skew ⁽³⁾		—	0.5	—	0.5	—	0.5	ns

NOTES:

1. See test circuit and waveforms.
2. Minimum limits are guaranteed but not tested on Propagation Delays.
3. Skew between any two outputs, of the same package, switching in the same direction. This parameter is guaranteed by design.
4. Propagation Delays and Enable/Disable times are with Vcc = 3.3V ±0.3V, Normal Range. For Vcc = 2.7V to 3.6V, Extended Range, all Propagation Delays and Enable/Disable times should be degraded by 20%.
5. This parameter is guaranteed but not tested.

TEST CIRCUITS AND WAVEFORMS

TEST CIRCUITS FOR ALL OUTPUTS



SWITCH POSITION

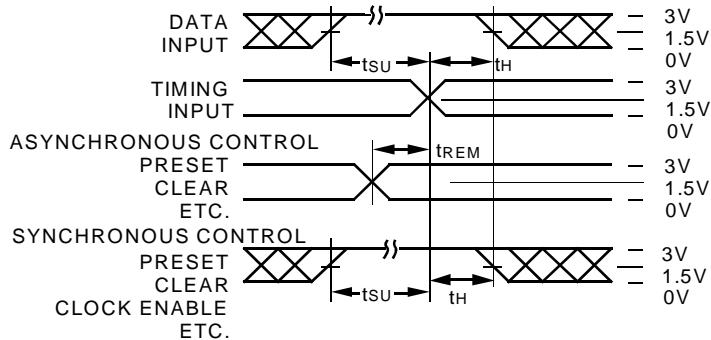
Test	Switch
Open Drain	
Disable Low	6V
Enable Low	
Disable High	GND
Enable High	
All Other Tests	Open

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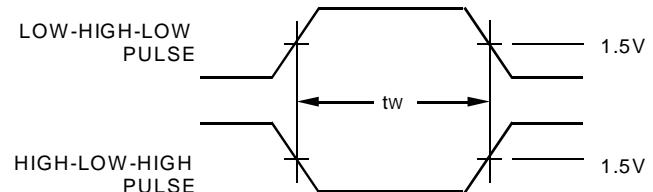
DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.
RT = Termination resistance: should be equal to Zout of the Pulse Generator.

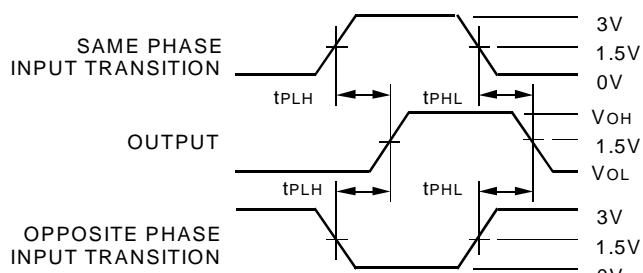
SET-UP, HOLD, AND RELEASE TIMES



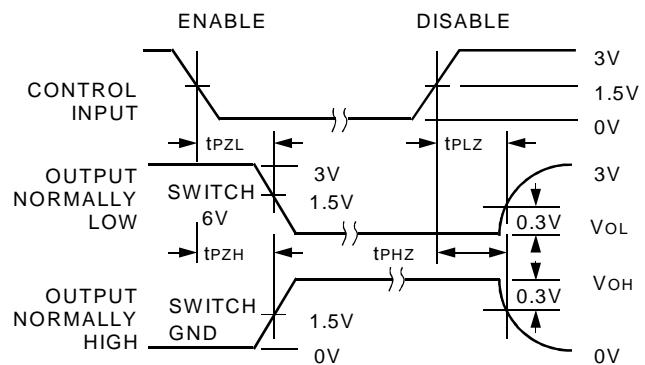
PULSE WIDTH



PROPAGATION DELAY



ENABLE AND DISABLE TIMES



NOTES:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
2. Pulse Generator for All Pulses: Rate $\leq 1.0\text{MHz}$; $t_f \leq 2.5\text{ns}$; $t_r \leq 2.5\text{ns}$.
3. If Vcc is below 3V, input voltage swings should be adjusted not to exceed Vcc.

ORDERING INFORMATION

IDT	XX	FCT	XXX	XXXX	X	
Temp. Range		Family		Device Type	Package	
					PV	Shrink Small Outline Package (SO48-1)
					PA	Thin Shrink Small Outline Package (SO48-2)
					PF	Thin Very Small Outline Package (SO48-3)
				245		Non-Inverting 16-Bit Bidirectional Transceiver
				245A		
				245C		
				163		Double-Density 3.3Volt
					74	-40°C to +85°C



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